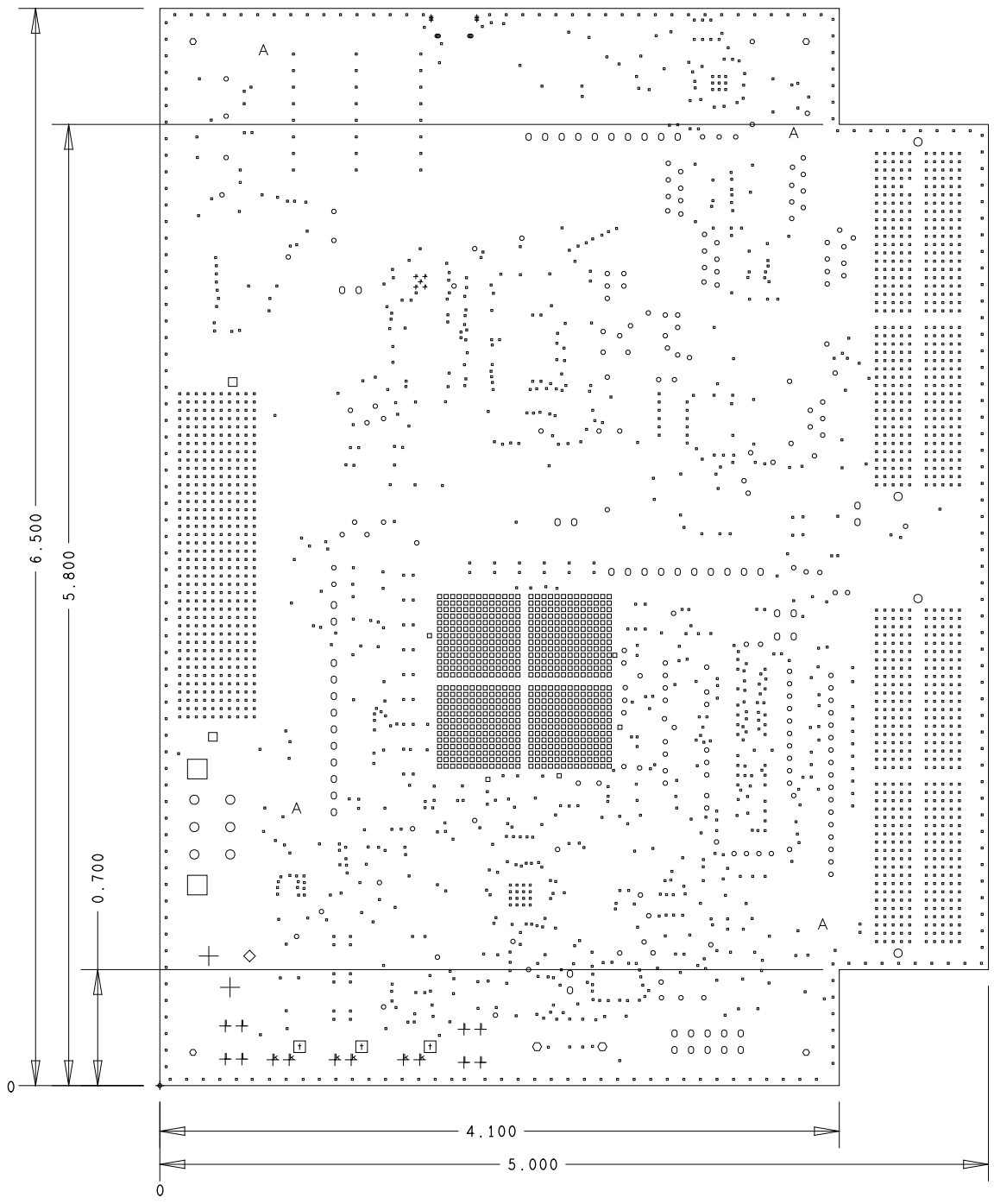
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
▫	8.0	+3.0/-8.0	PLATED	681
+	10.0	+0.0/-10.0	PLATED	5
▫	12.0	+3.0/-12.0	PLATED	2315
◦	21.654	+2.0/-2.0	PLATED	6
+	21.654	+3.0/-3.0	PLATED	8
◦	28.0	+3.0/-3.0	PLATED	191
+	35.039	+1.969/-1.969	PLATED	8
◦	42.0	+3.0/-3.0	PLATED	54
*	49.37	+2.992/-2.992	PLATED	6
○	55.0	+3.0/-3.0	PLATED	6
A	63.0	+3.0/-3.0	PLATED	4
┼	120.0	+3.0/-3.0	PLATED	2
◦	125.0	+3.0/-3.0	PLATED	4
◇	140.0	+3.0/-3.0	PLATED	1
○	40.0	+3.0/-3.0	NON-PLATED	2
⊡	43.307	+2.0/-0.0	NON-PLATED	3
○	50.0	+3.0/-3.0	NON-PLATED	4
▫	52.0	+3.0/-3.0	NON-PLATED	2
□	118.0	+3.0/-3.0	NON-PLATED	2



Primary Side Shown

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY - USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. UL94V MATERIAL REQUIRED. CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. MARK EFILE NUMBER ON THE FINISHED BOARD.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
6. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
7. MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
8. NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
9. FOIL OUTER OPTIONAL.
10. INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
11. TEARDROP VIAS AS NECESSARY.
12. THIEVING IS NOT ALLOWED.

PROCESS NOTES:

1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MIN MICROINCHES THK GOLD 2-6 MICROINCHES THK.
2. APPLY LPI OR LDI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
3. FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.
5. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.

INNER PLANE LAYERS TO BE 1/2 OZ. COPPER.
INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER.
OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.

LAYER STACKUP

.062" +/- 10%

- LAYER 1 - PRIMARY SIDE
- LAYER 2 - GND PLANE
- LAYER 3 - SIGNAL
- LAYER 4 - GND PLANE
- LAYER 5 - SIGNAL
- LAYER 6 - GND PLANE
- LAYER 7 - PWR PLANE
- LAYER 8 - PWR PLANE
- LAYER 9 - GND PLANE
- LAYER 10 - SIGNAL
- LAYER 11 - GND PLANE
- LAYER 12 - SIGNAL
- LAYER 13 - GND PLANE
- LAYER 14 - SECONDARY SIDE

CONTROLLED IMPEDANCE

EXTERNAL LAYERS

0.0055" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0039" WIDE/0.0056" SPACING 100 OHMS DIFFERENTIAL +/-10%
0.0045" WIDE/0.0055" SPACING 90 OHMS DIFFERENTIAL +/-10%

INTERNAL LAYERS

0.00475" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0039" WIDE/0.0083" SPACING 100 OHMS DIFFERENTIAL +/-10%

TEXAS INSTRUMENTS		
BOARD NAME:	DESCRIPTION: FAB DRAWING	
PROJECT #: DLP082	DATE: 13 FEB 2023	REVISION: REV C